

To all our customers

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Note : Mitsubishi Electric will continue the business operations of high frequency & optical devices and power devices.

Renesas Technology Corp.  
Customer Support Dept.  
April 1, 2003

# M5M5V408BFP,TP,KV

## 4194304-BIT (524288-WORD BY 8-BIT) CMOS STATIC RAM

### DESCRIPTION

The M5M5V408B is a family of low voltage 4-Mbit static RAMs organized as 524,288-words by 8-bit, fabricated by Mitsubishi's high-performance 0.25µm CMOS technology.

The M5M5V408B is suitable for memory applications where a simple interfacing, battery operating and battery

- Package:  
 M5M5V408BFP: 32 pin 525 mil SOP  
 M5M5V408BTP: 32 pin 400mil TSOP(II)  
 M5M5V408BKV: 32 pin 8mm x13.4mm STSOP

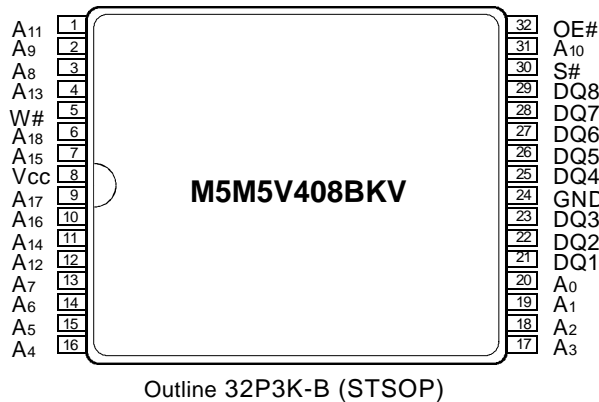
### FEATURES

- Single 2.7 ~ 3.6V power supply
- Small stand-by current: 0.3µA (3V,typ.)
- No clocks, No refresh
- Data retention supply voltage=2.0V to 3.6V
- All inputs and outputs are TTL compatible.
- Easy memory expansion by S#
- Common Data I/O
- Three-state outputs: OR-tie capability
- OE# prevents data contention in the I/O bus
- Process technology: 0.25µm CMOS

Version, Operating temperature	Part name (## stands for "FP", "TP" or "KV")	Power supply	Access time (max.)	Stand-by current I <sub>cc</sub> (PD), V <sub>cc</sub> =3.0V						Active current I <sub>cc1</sub> (3.0V, typ.*)
				Typical *		Limits (max.)				
				25°C	40°C	25°C	40°C	70°C	85°C	
Standard 0 ~ 70°C	M5M5V408B## -70H	2.7 ~ 3.6V	70ns	0.3µA	1µA	1µA	3µA	15µA	-	30mA (10MHz)
	M5M5V408B## -85H		85ns							
I-version -40 ~ +85°C	M5M5V408B##-70HI	2.7 ~ 3.6V	70ns	0.3µA	1µA	1µA	3µA	15µA	30µA	5mA (1MHz)
	M5M5V408B##-85HI		85ns							

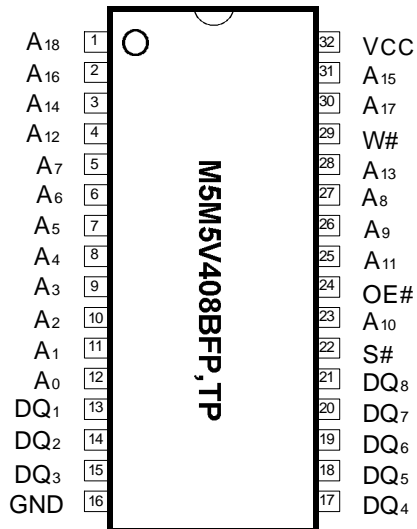
\*Typical values are sampled, and are not 100% tested.

### PIN CONFIGURATION (TOP VIEW)



Outline 32P3K-B (STSOP)

Pin	Function
A0 ~ A18	Address input
DQ1 ~ DQ8	Data input / output
S# ( $\bar{S}$ )	Chip select input
W# ( $\bar{W}$ )	Write control input
OE# ( $\bar{OE}$ )	Output enable input
Vcc	Power supply
GND	Ground supply



Outline 32P2M-A (SOP)  
32P3Y-H (TSOP II)

# M5M5V408BFP,TP,KV

## 4194304-BIT (524288-WORD BY 8-BIT) CMOS STATIC RAM

### FUNCTION

The M5M5408BFP,TP,KV is organized as 524,288-words by 8-bit. These devices operate on a single +2.7~3.6V power supply, and are directly TTL compatible to both input and output. Its fully static circuit needs no clocks and no refresh, and makes it useful.

A write operation is executed during the S# low and W# low overlap time. The address(A0~A18) must be set up before the write cycle

A read operation is executed by setting W# at a high level and OE# at a low level while S# are in an active

When setting S# at a high level, the chips are in a non-selectable mode in which both reading and writing are disabled. In this mode, the output stage is in a high-impedance state, allowing OR-tie with other chips. Setting the OE# at a high level, the output stage is in a high-impedance state, and the data bus contention problem in the write cycle is eliminated.

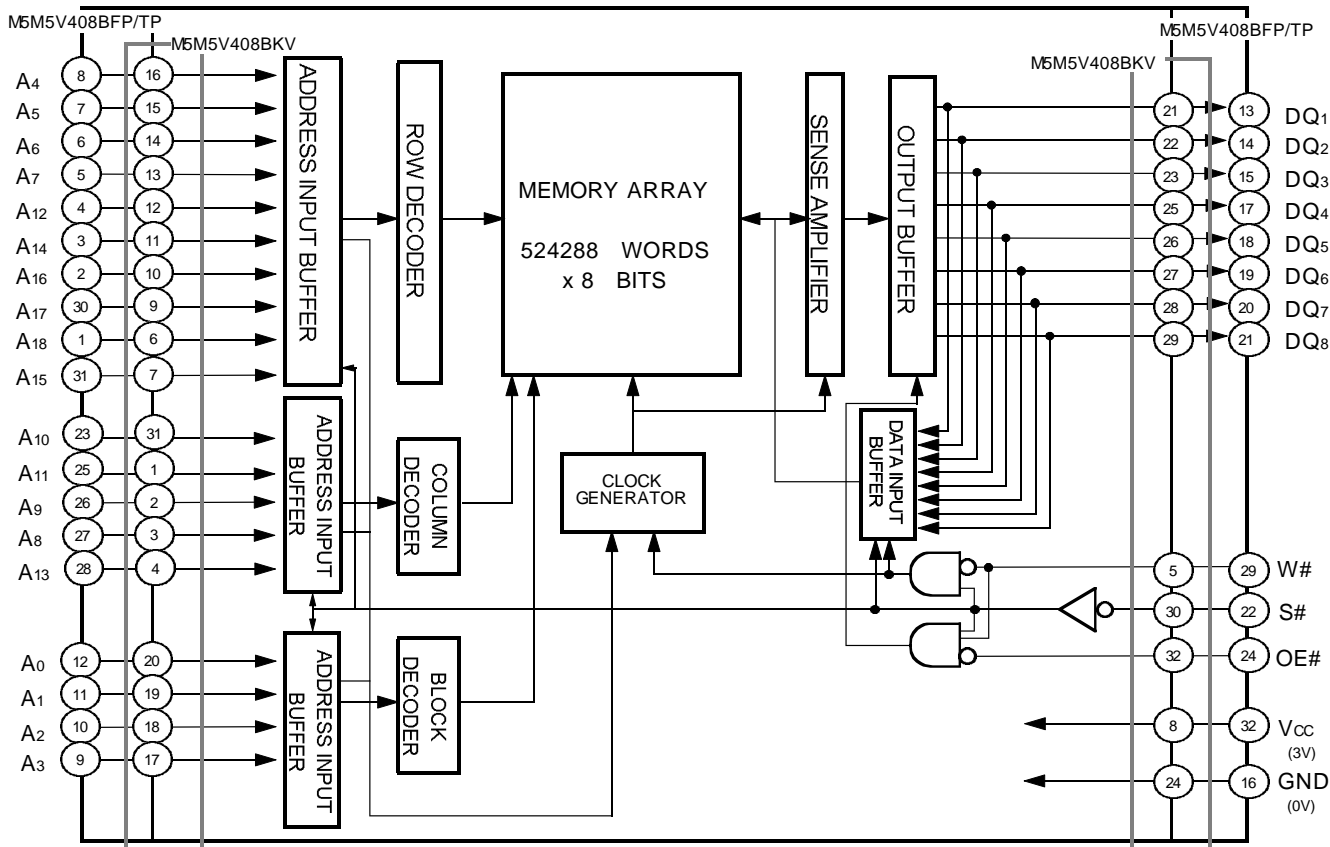
The power supply current is reduced as low as 0.3μA(25°C, typical), and the memory data can be held at +2V power supply, enabling battery back-up operation during power failure or power-down operation in the non-

### FUNCTION TABLE

S#	W#	OE#	Mode	DQ	Icc
H	X	X	Non selection	High-impedance	Standby
L	L	X	Write	Data input (D)	Active
L	H	L	Read	Data output (Q)	Active
L	H	H	Read	High-impedance	Active

note: "H" and "L" in this table mean VIH and VIL, respectively. "X" in this table should be "H" or "L".

### BLOCK DIAGRAM



**M5M5V408BFP,TP,KV****4194304-BIT (524288-WORD BY 8-BIT) CMOS STATIC RAM****ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Conditions	Ratings	Units
V <sub>CC</sub>	Supply voltage	With respect to GND	-0.5* ~ +4.6	V
V <sub>I</sub>	Input voltage	With respect to GND	-0.5* ~ V <sub>CC</sub> + 0.5	
V <sub>O</sub>	Output voltage	With respect to GND	0 ~ V <sub>CC</sub>	
P <sub>d</sub>	Power dissipation	T <sub>a</sub> =25°C	700	mW
T <sub>a</sub>	Operating temperature	Standard (Commercial temp.)	0 ~ 70	°C
		I-version (Industrial temp.)	- 40 ~ +85	
T <sub>stg</sub>	Storage temperature		- 65 ~ +150	°C

\* -3.0V in case of AC (Pulse width ≤ 30ns)

**DC ELECTRICAL CHARACTERISTICS**(V<sub>CC</sub>=2.7 ~ 3.6V, unless otherwise noted)

Symbol	Parameter	Conditions	Limits			Units		
			Min	Typ	Max			
V <sub>IH</sub>	High-level input voltage		2.2		V <sub>CC</sub> +0.3V	V		
V <sub>IL</sub>	Low-level input voltage		-0.3*		0.6			
V <sub>OH1</sub>	High-level output voltage 1	I <sub>OH</sub> = -0.5mA	2.4					
V <sub>OH2</sub>	High-level output voltage 2	I <sub>OH</sub> = -0.05mA	V <sub>CC</sub> -0.5V					
V <sub>OL</sub>	Low-level output voltage	I <sub>OL</sub> =2mA			0.4			
I <sub>I</sub>	Input leakage current	V <sub>I</sub> =0 ~ V <sub>CC</sub>			±1	μA		
I <sub>O</sub>	Output leakage current	S#=V <sub>IH</sub> or OE#=V <sub>IH</sub> , V <sub>I/O</sub> =0 ~ V <sub>CC</sub>			±1			
I <sub>CC1</sub>	Active supply current (AC, CMOS-level)	S# ≤ 0.2V Output-open Other inputs ≤ 0.2V or ≥ V <sub>CC</sub> -0.2V	f = 10MHz	-	30	45	mA	
			f = 1MHz	-	5	7		
I <sub>CC2</sub>	Active supply current (AC, TTL-level)	S#=V <sub>IL</sub> Output-open Other inputs=V <sub>IH</sub> or V <sub>IL</sub>	f = 10MHz	-	30	45		
			f = 1MHz	-	5	7		
I <sub>CC3</sub>	Stand by supply current (CMOS-level input)	V <sub>CC</sub> =3.6V, max. S# ≥ V <sub>CC</sub> -0.2V Other inputs=0~V <sub>CC</sub>	I-version	85°C	-	-	40	μA
			I-version, standard	70°C	-	-	20	
				40°C	-	1	5	
			I-version	0 ~ +25°C	-	0.3	2	
I <sub>CC4</sub>	Stand by supply current (TTL-level input)	S#=V <sub>IH</sub> , Other inputs= 0 ~ V <sub>CC</sub>	-	-	0.5	mA		

\* -3.0V in case of AC (Pulse width ≤ 30ns)

Note 1: Direction for current flowing into IC is indicated as positive (no mark).

Note 2: Typical values are sampled at V<sub>CC</sub>=3.0V, and are not 100% tested.**CAPACITANCE**(V<sub>CC</sub>=2.7 ~ 3.6V, unless otherwise noted)

Symbol	Parameter	Conditions	Limits			Units
			Min	Typ	Max	
C <sub>I</sub>	Input capacitance	V <sub>I</sub> =GND, V <sub>I</sub> =25mVrms, f=1MHz			8	pF
C <sub>O</sub>	Output capacitance	V <sub>O</sub> =GND, V <sub>O</sub> =25mVrms, f=1MHz			10	

# M5M5V408BFP,TP,KV

## 4194304-BIT (524288-WORD BY 8-BIT) CMOS STATIC RAM

### AC ELECTRICAL CHARACTERISTICS (V<sub>CC</sub>=2.7 ~ 3.6V, unless otherwise noted)

#### (1) TEST CONDITIONS

Supply voltage	2.7V~3.6V
Input pulse	V <sub>IH</sub> =2.4V, V <sub>IL</sub> =0.4V
Input rise time and fall time	5ns
Reference level	V <sub>OH</sub> =V <sub>OL</sub> =1.5V Transition is measured ±500mV from steady state voltage.(for t <sub>en</sub> ,t <sub>dis</sub> )
Output loads	Fig.1,CL=30pF CL=5pF (for t <sub>en</sub> ,t <sub>dis</sub> )

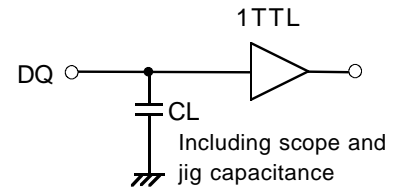


Fig.1 Output load

#### (2) READ CYCLE

Symbol	Parameter	Limits				Units
		-70H, -70HI		-85H, -85HI		
		Min	Max	Min	Max	
t <sub>CR</sub>	Read cycle time	70				ns
t <sub>a(A)</sub>	Address access time		70		85	ns
t <sub>a(S)</sub>	Chip select access time		70		85	ns
t <sub>a(OE)</sub>	Output enable access time		35		45	ns
t <sub>dis(S)</sub>	Output disable time after S# high	25			25	ns
t <sub>dis(OE)</sub>	Output disable time after OE# high	25			25	ns
t <sub>en(S)</sub>	Output enable time after S# low	10		10		ns
t <sub>en(OE)</sub>	Output enable time after OE# low	5		5		ns
t <sub>v(A)</sub>	Data valid time after address	10		10		ns

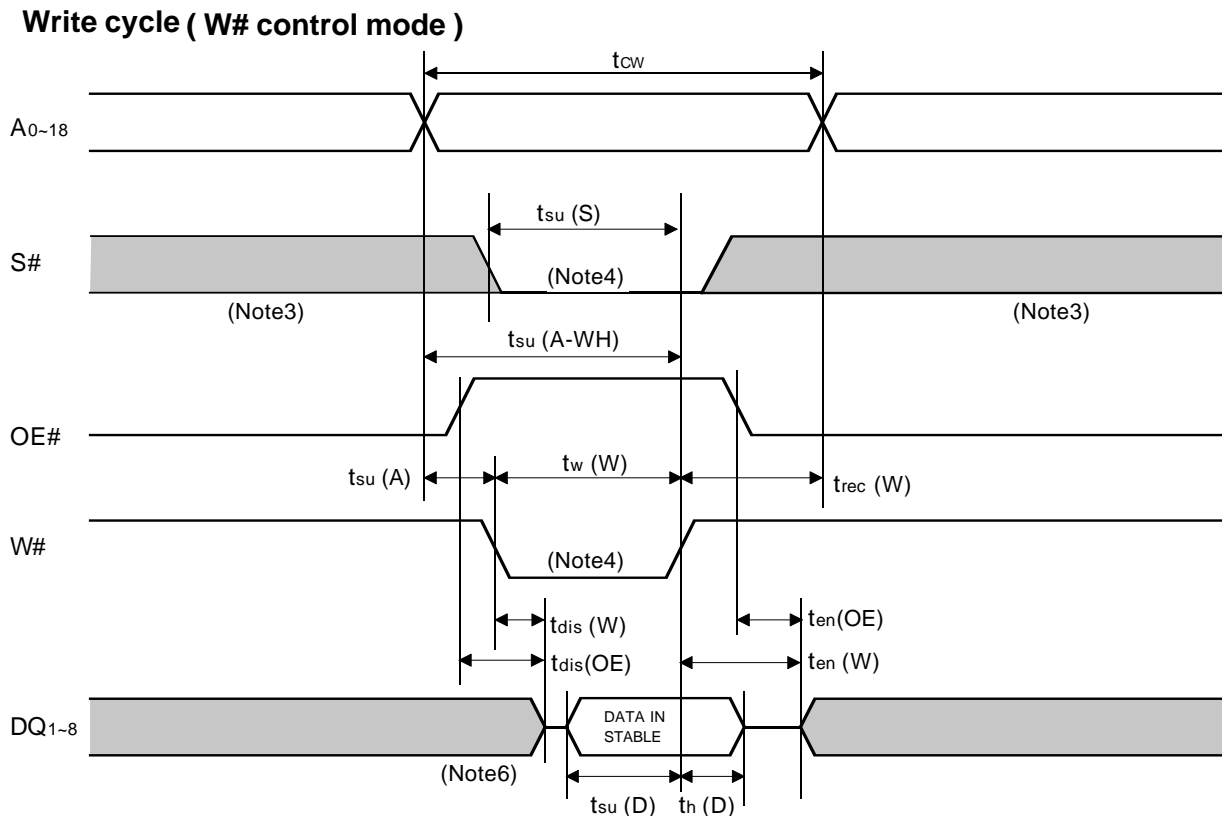
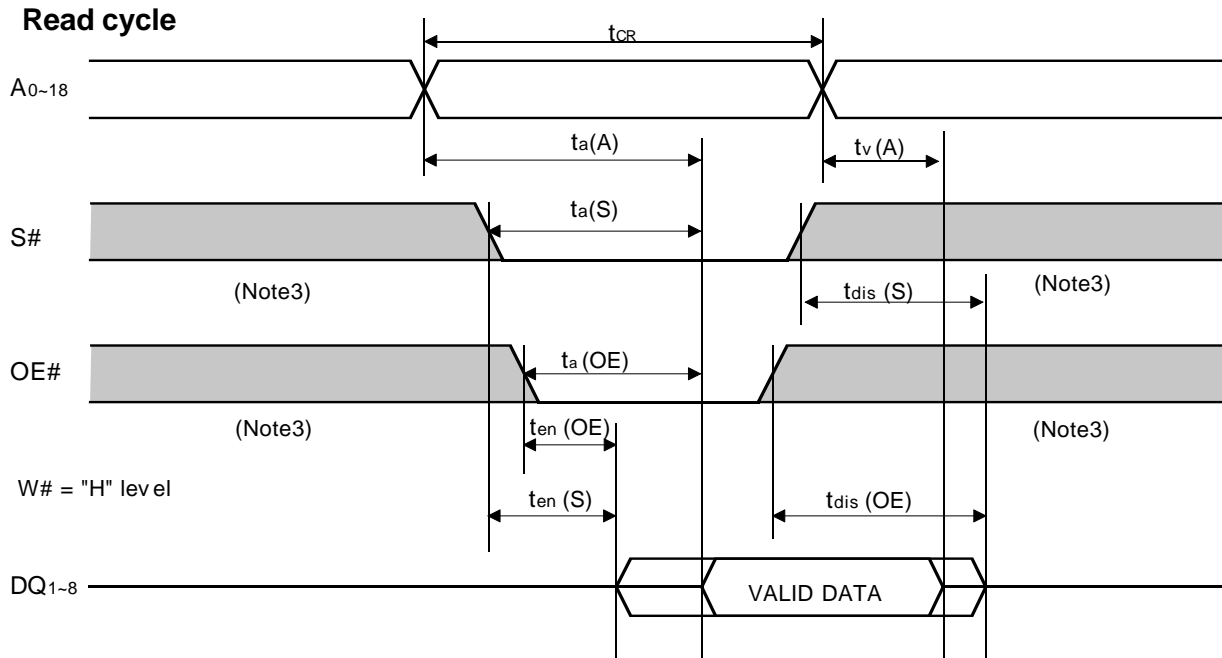
#### (3) WRITE CYCLE

Symbol	Parameter	Limits				Units
		-70H, -70HI		-85H, -85HI		
		Min	Max	Min	Max	
t <sub>cw</sub>	Write cycle time	70		85		ns
t <sub>w(W)</sub>	Write pulse width	55		55		ns
t <sub>su(A)</sub>	Address set up time	0		0		ns
t <sub>su(A-WH)</sub>	Address set up time with respect to W# high	65		65		ns
t <sub>su(S)</sub>	Chip select set up time	65		65		ns
t <sub>su(D)</sub>	Data set up time	35		35		ns
t <sub>h(D)</sub>	Data hold time	0		0		ns
t <sub>rec(W)</sub>	Write recovery time	0		0		ns
t <sub>dis(W)</sub>	Output disable time after W# low		25		25	ns
t <sub>dis(OE)</sub>	Output disable time after OE# high		25		25	ns
t <sub>en(W)</sub>	Output enable time after W# high	5		5		ns
t <sub>en(OE)</sub>	Output enable time after OE# low	5		5		ns

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4194304-BIT (524288-WORD BY 8-BIT) CMOS STATIC RAM

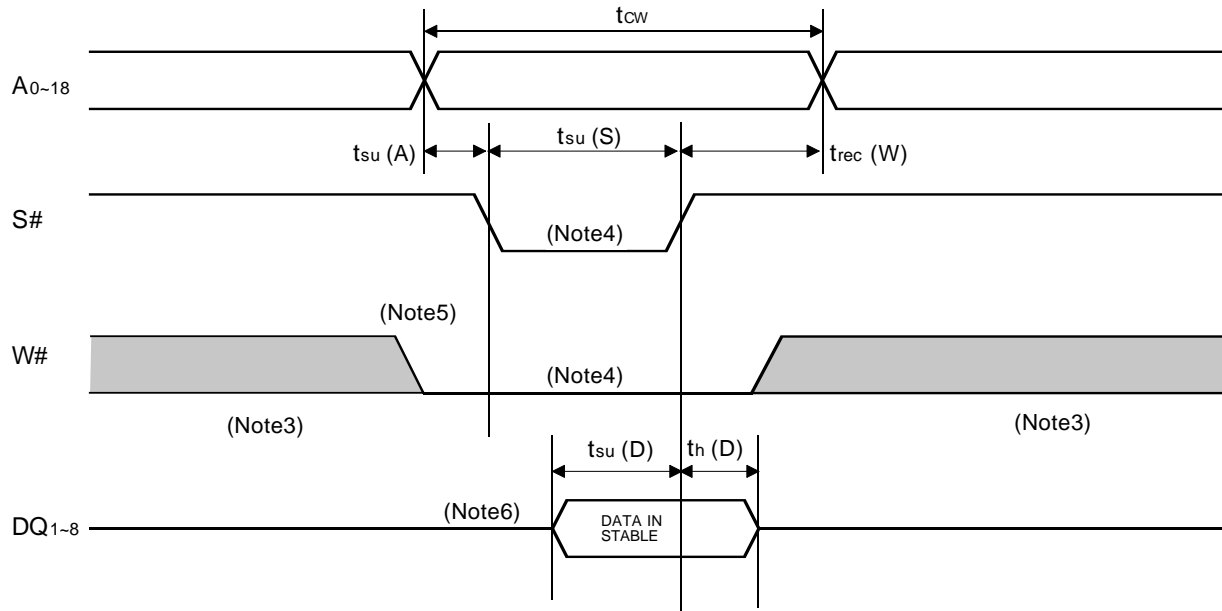
## (4) TIMING DIAGRAMS



# M5M5V408BFP,TP,KV

4194304-BIT (524288-WORD BY 8-BIT) CMOS STATIC RAM

## Write cycle (S# control mode)



Note 3: Hatching indicates the state is "don't care".

Note 4: A Write occurs during the overlap of a low S# and a low W#.

Note 5: If W# goes low simultaneously with or prior to S#, the output remains in the high impedance state.

Note 6: Don't apply inverted phase signal externally when DQ pin is in output mode.

# M5M5V408BFP,TP,KV

4194304-BIT (524288-WORD BY 8-BIT) CMOS STATIC RAM

## POWER DOWN CHARACTERISTICS

### (1) ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Test conditions	Limits			Units		
			Min	Typ.	Max			
V <sub>CC</sub> (PD)	Power down supply voltage		2.0			V		
V <sub>I</sub> (S)	Chip select input S#		2.0			V		
I <sub>CC</sub> (PD)	Power down supply current	V <sub>CC</sub> =3.0V, S# ≥ V <sub>CC</sub> -0.2V, Other inputs = 0 ~ V <sub>CC</sub>	I-version	85°C	-	-	30	μA
			Standard,	70°C	-	-	15	
			I-version	40°C	-	1*	3	
			Standard	0~ 25°C	-	0.4*	1	
			I-version	-40~ 25°C	-	0.4*	1	

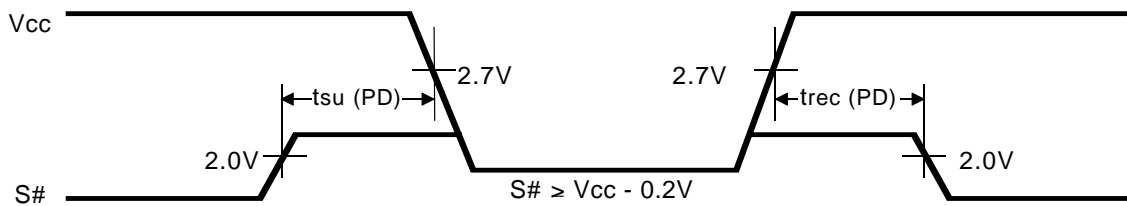
\*Typical values are sampled, and are not 100% tested.

### (2) TIMING REQUIREMENTS

Symbol	Parameter	Test conditions	Limits			Units
			Min	Typ.	Max	
t <sub>SU</sub> (PD)	Power down set up time		0			ns
t <sub>REC</sub> (PD)	Power down recovery time		5			ms

### (3) TIMING DIAGRAM

S# control mode





**M5M5V408BFP,TP,KV**

4194304-BIT (524288-WORD BY 8-BIT) CMOS STATIC RAM

**Revision History**

<u>Revision No.</u>	<u>History</u>	<u>Date</u>	<u>Remarks</u>
K0.1e	The first edition	Mar. 5, 1998	Preliminary
K0.2e	Added M5M5V408BFP/TP/RT	Jul.30, 1998	Preliminary
K1.0e	The first product version	Sep.7, 1998	---
K2.0e	1) Speed items revised: 70ns added and 100ns deleted 2) lcc3 and lcc(PD) limits revised	Mar.10,1999	---
3.0e	1) Product lineup revised 2) Symbol notations revised: $\overline{S}$ -> S#, $\overline{W}$ -> W#, $\overline{OE}$ -> OE#	Feb.12, 2002	---

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